

**IN THE ABSTRACT OF THE DISCLOSURE**

Please amend the Abstract as follows:

**ABSTRACT OF THE DISCLOSURE**

A ~~wire bonding substrate is disclosed.~~ The wire-bonding substrate includes a first wire-bond pad and a first via that is disposed directly below the first wire-bond pad in the in the wire-bonding substrate. A package ~~is also disclosed that~~ includes a die that is coupled to the first wire-bonding pad. The package can include a larger substrate that is coupled to the wire-bonding substrate through an electrical connection such as a solder ball. A process of forming the wire-bonding substrate ~~is also disclosed.~~ The process includes via formation to stop on the wire-bond pad. A method of assembling a microelectronic package ~~is also disclosed that~~ includes coupling the die to the wire-bond pad. A computing system ~~is also disclosed that~~ includes the wire-bonding substrate.